

June 7th, 2019

Business Segment: ELECTRONICS

**MacDermid Alpha's Assembly Division to Present Low Temperature Soldering Solutions
at Hilpert Electronics Customer Technical Seminar**

(Waterbury, CT USA) – June 7th, 2019 – The Assembly division of MacDermid Alpha Electronics Solutions, a world leader in the production of electronics soldering and bonding materials, will present its latest low temperature soldering technologies at the upcoming 'Paste Printing 4.0' customer technical seminar hosted by Hilpert Electronics, ALPHA® distributor for Switzerland, on Wednesday 19th June 2019.

Alan Plant, Customer Technical Service Coordinator, Europe for the Assembly Division of MacDermid Alpha, will present the latest [ALPHA® Low Temperature Solutions](#) at the event, including the revolutionary ALPHA® OM-550 HRL1 low temperature solder paste. "ALPHA® OM-550 low temperature chemistry paired with the ALPHA® HRL1 alloy, enables a vast improvement in drop shock and thermal cycling performance and mechanical reliability versus existing low temperature alloys", comments Alan. "Furthermore, with a minimum peak temperature of only 185°C vs 245°C, ALPHA® OM-550 HRL1 solder paste reduces energy consumption in the SMT process leading to a significant reduction in energy costs. The paste also delivers an increase in production yield and a reduction in component warpage."

The seminar will also include presentations on how to achieve a cost reduction in SMT soldering by selecting the optimal soldering materials, as well as live machine demos. For more information on the Paste Printing 4.0 seminar and to register for the event please visit the [Hilpert Electronics Website](#).

To learn more about [Alpha's Low Temperature Technologies](#) visit the [MacDermid Alpha website](#).

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